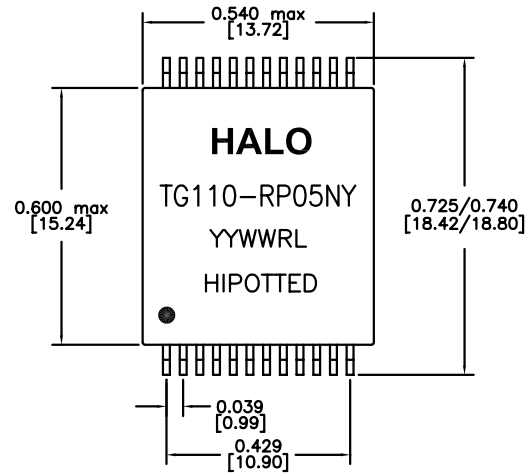
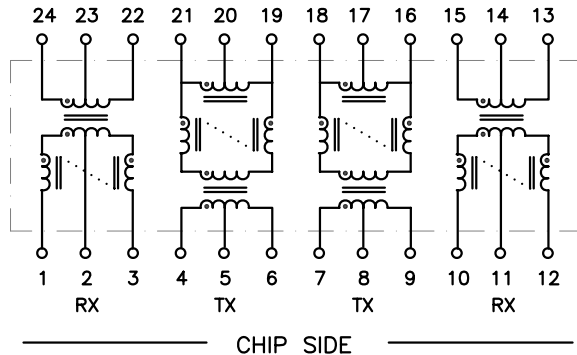


DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



PART NO. : TG110-RP05NYRL

24PIN 0.039" LEAD PITCH SMT PACKAGE
FAST ETHERNET 10/100BASE-TX MAGNETICS
COMPLIANT WITH IEEE802.3af STANDARD

350mA CURRENT CARRYING CAPACITY
ON LINE SIDE FOR PoE APPLICATIONS

RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

OPERATING TEMPERATURE 0/+70°C

ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO 1CT:1CT±2%

OCL (100KHz,0.1Vrms,8mA)
P4-6,P7-9,P15-13,P24-22

350µH min

DCR
P4-6,P7-9,P15-13,P24-22

1.0Ω max

INSERTION LOSS

0.1-100MHz

-1.1dB max

RETURN LOSS

0.5-30MHz

-18dB min

40MHz

-16dB min

50MHz

-13dB min

60-80MHz

-12dB min

CMR 0.1-100MHz

-40dB typ

CROSSTALK 0.1-100MHz

-40dB typ

ISOLATION

1,500Vrms



HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE ISOLATION MODULE

FOR FAST ETHERNET, PoE

PART NO. TG110-RP05NYRL

SCALE NONE

PAGE 1 OF 2

SIGNATURES

DRAWN PETER LU

CHECKED LEI KEONG

APPROVED PETER LU

FILE RP05NYRL.DWG

DATE

4/27/05

5/6/06

5/6/06

REV.

A

B

DESC.

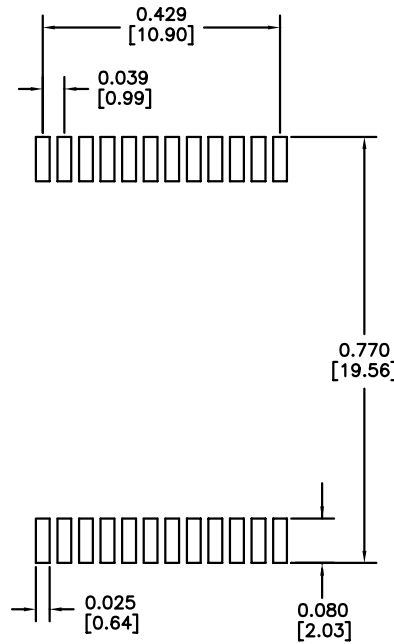
FIRST ISSUE

PROD. RELEASE

DATE

4/27/05

5/6/06



RECOMMENDED SOLDER PAD DIMENSIONS
DIMENSIONS: Inch [mm]

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST ETHERNET, PoE		DRAWN PETER LU	4/27/05	A	FIRST ISSUE	4/27/05
PART NO.	TG110-RP05NYRL		CHECKED LEI KEONG	5/6/06	B	PROD. RELEASE	5/6/06
SCALE	NONE	PAGE 2 OF 2	APPROVED PETER LU	5/6/06			
			FILE RP05NYRL.DWG				